

## N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
60	0.075 at V <sub>GS</sub> = 10 V	4.0	2.1 nC			
60	0.086 at V <sub>GS</sub> = 4.5 V	3.8	2.1 NC			

#### **FEATURES**

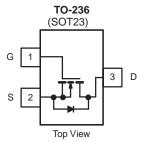
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

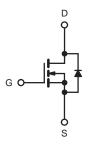
# **RoHS** HALOGEN

FREE

#### **APPLICATIONS**

- Battery Switch
- DC/DC Converter





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A =$	25 °C, unless oth	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	60	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	¬	
	T <sub>C</sub> = 25 °C		4.0	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C	1-	3.4	
Continuous Diam Current (1) = 130 °C)	T <sub>A</sub> = 25 °C	ID	3.1 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		2.5 <sup>b, c</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	12	^	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l <sub>a</sub>	1.39	
Continuous Source-Dialii Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.91 <sup>b, c</sup>	
Avalanche Current		I <sub>AS</sub>	6	
Single-Pulse Avalanche Energy  L = 0.1 mH		E <sub>AS</sub>	1.8	mJ
	T <sub>C</sub> = 25 °C		1.66	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.06	w
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' D	1.09 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		0.7 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	R <sub>thJA</sub>	90	115	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	60	75	C/VV	

- a. Based on T<sub>C</sub> = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 120 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 vA		55		mV/°0
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I <sub>D</sub> = 250 μA		- 5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	^
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	8			Α
	В	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A		0.075		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$		0.086		Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15V, I <sub>D</sub> = 1.9 A		5		S
Dynamic <sup>b</sup>					L	
Input Capacitance	C <sub>iss</sub>			180		
Output Capacitance	C <sub>oss</sub>			22		1
Reverse Transfer Capacitance	C <sub>rss</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		13		pF
T. 10 . 0		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A		4.2	4.2 6.1	nC
Total Gate Charge	Q <sub>g</sub>			2.1	3.2	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.9 \text{ A}$		0.7		
Gate-Drain Charge	$Q_{gd}$			1		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.6	2.2	5.1	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			4	6	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 20 $\Omega$		10	15	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ 1.5 A, $V_{GEN}$ = 10 V, $R_G$ = 1 $\Omega$		10	15	
Fall Time	t <sub>f</sub>			7	10.5	
Turn-On Delay Time	t <sub>d(on)</sub>			15	23	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 20 $\Omega$		16	24	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 1.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 1 \Omega$		11	17	ns
Fall Time	t <sub>f</sub>			11	17	1
<b>Drain-Source Body Diode Characteristi</b>	cs			<u>I</u>		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.19	_
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				7	A
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.5 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			15	23	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			10	15	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 1.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		
Reverse Recovery Rise Time	t <sub>b</sub>			3		ns

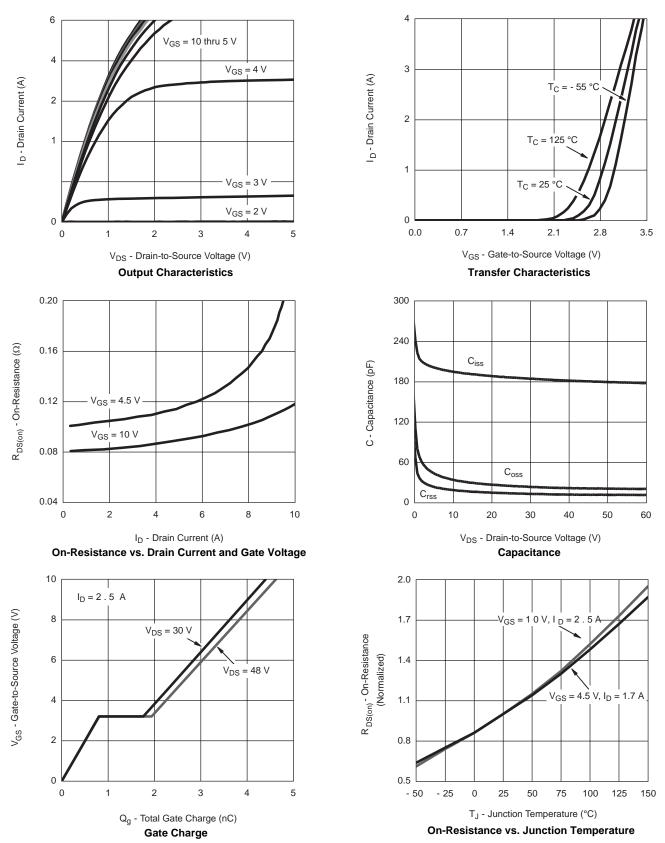
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

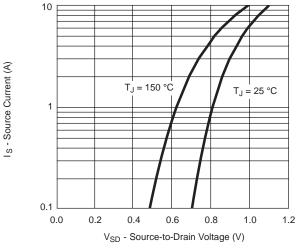


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

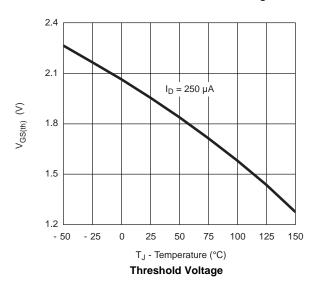




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



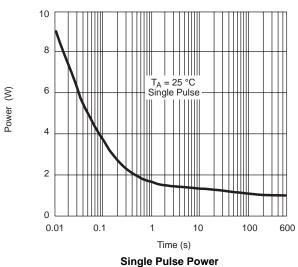
#### Source-Drain Diode Forward Voltage

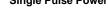


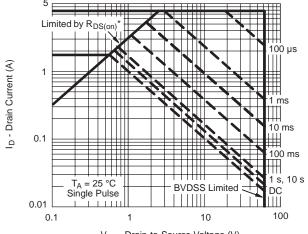
0.35
0.25
0.20
0.20  $T_{J} = 125 \, ^{\circ}\text{C}$ 0.10  $T_{J} = 2.5 \, ^{\circ}\text{C}$ 

V<sub>GS</sub> - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage







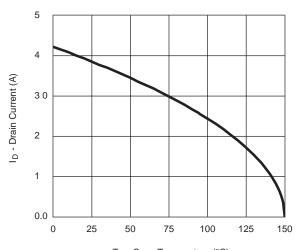
V<sub>DS</sub> - Drain-to-Source Voltage (V)

Safe Operating Area

<sup>\*</sup>  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

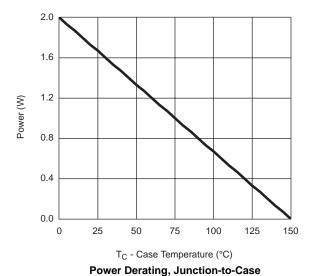


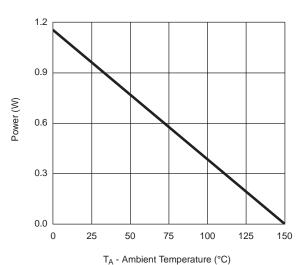
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T<sub>C</sub> - Case Temperature (°C)

#### Current Derating\*



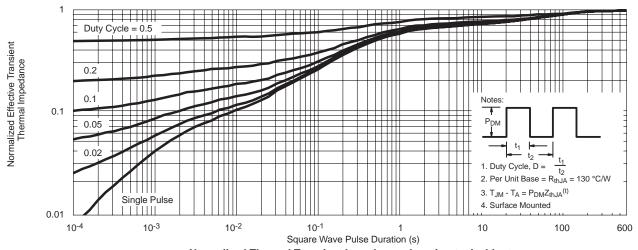


Power Derating, Junction-to-Ambient

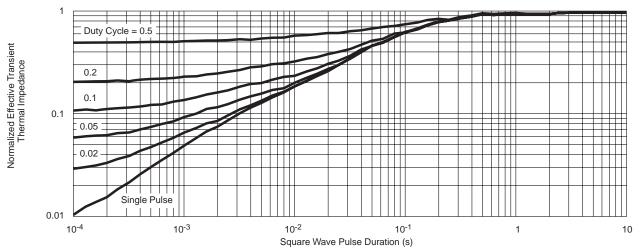
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

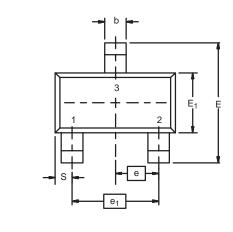


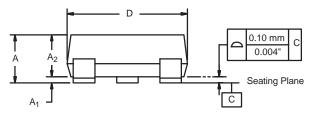
Normalized Thermal Transient Impedance, Junction-to-Foot

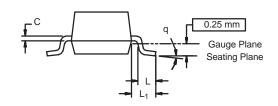


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### SOT-23 (TO-236): 3-LEAD





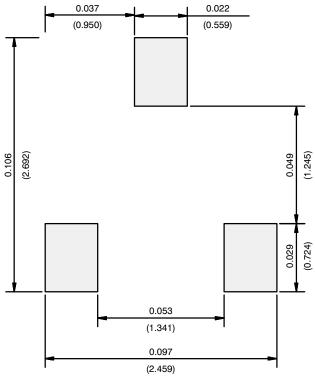


Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01				

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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